



Silicon Wafer Japan TC Chapter

In Conjunction with SEMICON Japan 2025

Thursday, December 18, 2025

Room 904, TFT Building East Wing 9F, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

9:00 PM — 12:00 PM JST

AGENDA

1 Welcome/Call to Order

- 1.1 Introductions
- 1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)
- 1.3 Agenda Review

2 Review of Previous Meeting Minutes

3 Technical Committee Award

4 Liaison Report

- 4.1 Japan Regional Standards Committee (JRSC)
- 4.2 Global Coordinating Subcommittee (GCS)
- 4.3 Europe TC Chapter
- 4.4 North America TC Chapter

5 Staff Report

6 Ballot Review

- 6.1 Doc.#7392, Line Item Revision to SEMI M89-0721, Test Method for Recombination Lifetime of the Epilayer of the Silicon Epitaxial Wafer (p/p+, n/n+) by the Short Wavelength Excitation Microwave Photoconductive Decay Method
- 6.2 Doc.#7395, Reapproval of SEMI M67-0720 - Test Method for Determining Wafer Near-Edge Geometry from a Measured Thickness Data Array Using the ESFQR, ESFQD, and ESBIR Metrics
- 6.3 Doc.#7396, Reapproval of SEMI M68-0720 - Test Method for Determining Wafer Near-Edge Geometry from a Measured Height Data Array Using a Curvature Metric, ZDD

- 6.4 Doc.#6570C, New Standard: Guide for Measuring Bulk Micro Defect Density and Denuded Zone Width in Annealed Silicon Wafers by a Laser-Scattering Tomography Technique

7 Subcommittee & Task Force Reports

- 7.1 International Advanced Wafer Geometry Task Force
- 7.2 International/ Japan Test Method Task Force
- 7.3 International Advanced Surface Inspection Task Force
- 7.4 International Polished Wafers Task Force
- 7.5 International Epitaxial Wafers Task Force
- 7.6 International Annealed Wafers Task Force
- 7.7 International SOI Wafers Task Force
- 7.8 International Terminology Task Force

8 Old Business

- 8.1 Project Period Review
- 8.2 5-year Review
 - SEMI M90-0821, Test Method for Bulk Micro Defect Density and Denuded Zone Width in Annealed Silicon Wafers by Optical Microscopy After Preferential Etching

9 New Business

- 9.1 Leadership Change

10 Action Item Review

10.1 Open Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
SW20240829-01	SEMI Staff	To have a training session of Connect@SEMI for TF leaders.
SW20250829-01	Int'l Test Method TF	To submit M89 Line Item Revision Ballot for Cycle 8,2025.
SW20250829-02	SEMI Staff	To send SNARF for M85 Major Revision to Silicon Wafer Global TC members for 2 weeks review.
SW20250829-03	SEMI Staff	To request Int'l ASI TF to report their activities at TC Chapter meeting.

10.2 New Action Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>



11 Next Meeting and Adjournment

11.1 The next meeting is scheduled for <date> at <event/location>.